



Plasma Technology and Its Applications

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Deadline for manuscript
submissions:

closed (20 March 2023)

Message from the Guest Editor

We are inviting submissions to the Special Issue titled “Plasma Technology and Its Applications”.

Plasma technology is commonly used in many fields such as microelectronics, synthesis of nanomaterials, nitrogen fixation, biomedicine, environment protection, and surface modification of polymers. The development of plasma sources, the governing physics and chemistry of plasma, experimental and numerical diagnostics of plasma, and recent applications of plasma are attracting an increasing amount of interest from the research community. In any case, the authors should demonstrate that plasma technology dominates their work, and their research should point to the implementation of new ideas.

In this Special Issue, we invite submissions exploring cutting-edge research and recent advances in the fields of plasma technology and its applications. Both theoretical and experimental studies are welcome, as well as comprehensive review and survey papers.

Prof. Dr. Dawei Liu
Guest Editor





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Editor-in-Chief

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Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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